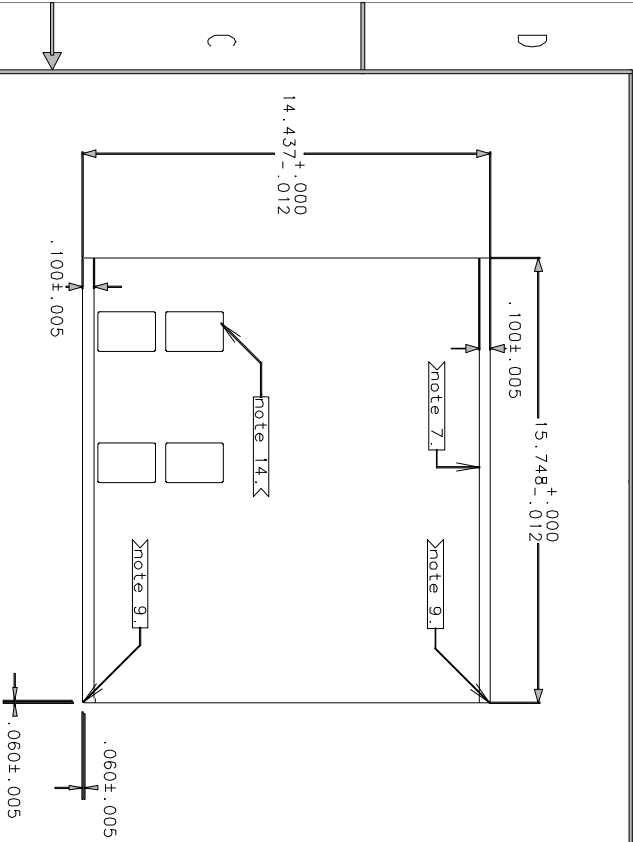


Board Thickness  
0.093 +/- 0.008

Board Characteristics :

- All dimensions are given in inches unless specified otherwise.
- Material: FR4, Tg>170C.
- Minimum Trace Width 0.008" on all layers.
- Minimum Clearance 0.007" on all layers.
- 1 oz copper for all Trace and Power Layers.
- Apply Solder and Solder Mask over bare copper.
- Board Thickness: 0.093 +/- 0.008".
- Mill the Top and Bottom 0.1" of board.
- on the solder side to a thickness of 0.062" +/- 0.008".
- Silkscreen on Component and Solder Sides.
- 45 degree chamfer.
- Hole diameter tolerances : +/- 0.003" unless specified otherwise.
- Hole diameter spacing : as specified.
- Impedance : 55 Ohm +/- 5 Ohm for signal traces on all layers.
- Perform TDR test and present test results.
- There are 4 cutouts.



BOARD'S DRILL SCHEDULE (inches)

SYMBOL	FHS	COUNT	PLATED	TOLERANCE	COMMENT
○	.02	2511	YES	---	
⊖	.033	312	YES	---	
⊖	.035	924	YES	---	
⊖	.041	488	YES	---	
⊖	.052	2	YES	---	
⊖	.057	6	YES	---	
⊖	.09	12	NO	---	
□	.106	33	NO	---	
□	.113	12	NO	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES FRACTIONS ARE IN INCHES DECIMALS ARE IN INCHES		CONTRACT NO.		ENRICO FERMI INST. UNIV. OF CHICAGO ELECTRONICS DEVELOPMENT GROUP	
DO NOT SCALE DRAWING	ALL DIMENSIONS ARE IN INCHES	APPROVALS	DATE	TITLE	
		DRAM M. Bogdan	4/5/04	CDF L2 FmOut board	
		CHECKED M. Bogdan	4/5/04	Specification Drawing	
FINISH	ISSUED	SCALE	SHEET	DRG. NO.	REV.
		B	1 of 1	A-2542	B